

a first storage portion provided on a first surface of said main body for storing the semiconductor integrated circuit device, said first storage portion having a first wall surface adapted to be arranged around the semiconductor integrated circuit device when the semiconductor integrated device is stored in said first storage portion,

wherein said first wall surface has a first area and a second area, said first area being inclined at an angle so as to support an edge of the package of the semiconductor integrated circuit device and to prevent said first wall surface from coming into contact with the wiring terminals of the semiconductor integrated circuit device when the semiconductor integrated circuit device is stored in said first storage portion, and said second area extending from said first area in a direction away from said first surface of said main body, wherein said second area is inclined at an angle larger than the angle of first area.

Please add the following new claims:

10. (New) A tray according to claim 1, wherein said first area is inclined at an angle between 40 degrees and 70 degrees.

11. (New) A tray according to claim 1, wherein said second area is inclined at an angle between 85 degrees and 90 degrees.

12. (New) A tray according to claim 1, wherein said first area is inclined at an angle between 40 degrees and 70 degrees, and said second area is inclined at an angle between 85 degrees and 90 degrees.

*Sub 2*  
13. (New) A tray for storing a semiconductor integrated circuit device having a package and wiring terminals on a lower surface of the package, said tray comprising:

a substantially planar main body;

a first storage portion provided on a first surface of said main body for storing the semiconductor integrated circuit device, said first storage portion having a first wall surface adapted to be arranged around the semiconductor integrated circuit device when the semiconductor integrated device is stored in said first storage portion, wherein said first wall surface has a first area which is inclined at an angle so as to support an edge of the package of the semiconductor integrated circuit device and to prevent said first wall surface from coming into contact with the wiring terminals of the semiconductor integrated circuit device when the semiconductor integrated circuit device is stored in said first storage portion; and

a second storage portion provided on a second surface of said main body opposite to said first storage portion, wherein said second storage portion can store a semiconductor integrated circuit device with wiring terminals thereof facing upward when said tray is turned over, and

wherein when two of said trays are aligned in a stacked relationship, said second storage portion of one tray cooperates with said first storage portion of the other tray to form a space for storing the semiconductor integrated circuit device.

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14. (New) A tray according to claim 13, wherein said second storage portion has a second wall surface adapted to be arranged around the semiconductor integrated circuit device when the semiconductor integrated circuit device is stored in said second storage portion with the wiring terminals thereof facing upward, and

wherein said second wall surface has a third area which is inclined at an angle so as to support an edge of the package of the semiconductor integrated circuit device when the semiconductor integrated circuit device is stored in said second stage portion.

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15. (New) A tray according to claim 13, further comprising positioning means for positioning said stacked trays to each other.

Sub 13

16. (New) A tray according to claim 13, wherein said main body includes a plurality of projecting pieces provided on said second surface thereof for defining said second storage portion, and wherein each of said projecting pieces has a wall surface for serving as said second

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~~wall surface, whereby said wall surfaces of said projecting pieces respectively support corners of the rectangular package of the semiconductor integrated circuit device.~~

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